

# QUICK SELECTION GUIDE

Standard / Approval	HDAS	HILINX <sup>1,905</sup>	SMASH	HDB <sup>3</sup> /HSB <sup>3</sup>	R-VPX	R-SATA	127/HE8
MIL-DTL-55302		M55302/190 to /193					M55302/140 to /155 NFC UTE 93424/ HE801-804-807
NFC-UTE							
SATA						SATA 3.0	
VITA					VITA 46, 66, 67		
RoHS	•	•	Not available for SMT version	•	•	•	•
<b>Board configuration</b>							
Motherboard to daughterboard	•	•	•	•	•	•	•
Mezzanine	•	•	•	•	•	•	•
Stacker	•	•	•	•	•	•	•
Board to cable	Test only	Test only	Test only	•			•
Extender / PC						•	•
<b>Contact termination</b>							
Press fit / compliant	•	•	•		•		
Thru hole soldering	•	•	•	•		•	•
Surface mount			•			•	
Crimping				•			•
Solder cup	Test only	Test only	Test only				•
<b>Contact technology</b>							
Starclip 6-fines	•	•	•				
Brush				•			
Stamped and formed					•		•
Micro-hyperboloid						•	
Lateral displacement compatible			Upon request				
<b>Technical features / accessories</b>							
Guiding devices	•	•	•	•	•	•	•
Polarization keys / keying	•	•	•	•	•		•
Locking system	•	•	•	•			•
Rackable solution			Upon request				
<b>Arrangements</b>							
Signal	•	•	•	•	•	•	•
Differential pair				•	•		
Power					•	•	•
Coaxial			Upon request		•		•
Optical			Upon request		•		•
<b>Pitch / contact pattern</b>							
Staggered grid	1,905 [.075] 0,9525 [.0375] offset	1,905 [.075] 0,9525 [.0375] offset		1,72 x 1,52 [.070x.060]		•	2,54 [.100] 1,27 [.050] offset
Square grid					1,8 x 1,8 [.039x.039]		
Chevron grid			1,905 [.075] 0,635 [.025] offset				
<b>Contacts number</b>							
1 row						7	
2 rows	Under development	10 to 100				22	17 to 96
3 rows	50, 77, 119, 152	11 to 206					80, 144
4 rows	102, 202		154, 258	40, 60, 80, 120, 160			
5 rows	253						
6 rows			132, 150, 264, 300, 396, 450				
Other					8 or 16 columns 3U or 6U		
<b>Electrical</b>							
Current rating per contacts (A)	4,5	3	3	2	1,5		3
Dielectric Withstanding Voltage (Vrms)	750	750	1000	750			1000
Max data rate (Gbps)	4	4		6,25	10	6,25	Not applicable
<b>Mechanical</b>							
Electrical security / Backoff	1,2mm [.047 in]	0,8mm [.031in]	1,2mm [.047 in]				1 mm [.039in]
Mating / Unmating force (g)	95	95	95	45			180
Durability	500	500	500	100 000	500	20 000	500
<b>Environmental</b>							
Salt spray (hours)	96	96	96	48	48		96
Temperature range (°C)	-65 / +150	-65 / +150	-65 / +150	-65 / +125	-55 / +105		-55 / +125
<b>Material / plating</b>							
Active area (gold thickness)	1µm [.039µin]	1.3µm [.051µin]	1.3µm [.051µin]	1.3µm or 0,5µm [.050µin or .020µin]	1.3µm or 0,75µm [.050µin or .030µin]		1µm [.039µin]
Termination area	Tin lead, bright pure tin, mat tin, gold, Silver-tin	Tin lead, lead free or gold	Tin lead, lead free or gold	Tin-lead, pure tin or gold	Tin-lead or lead free	Gold or tin lead dip	Tin-lead or lead free
Contact	Brass alloy	Brass alloy	Brass alloy	Beryllium copper	Copper alloy		CuSn9P or CuZn
Housing	LCP thermoplastic	LCP thermoplastic	LCP thermoplastic	LCP thermoplastic	LCP thermoplastic		DAP thermoset